

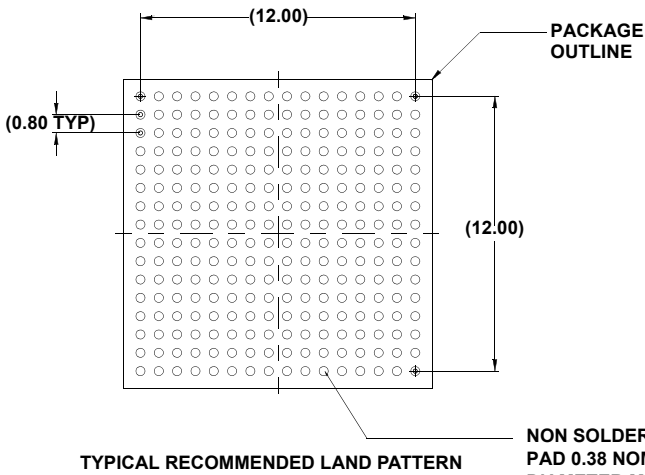
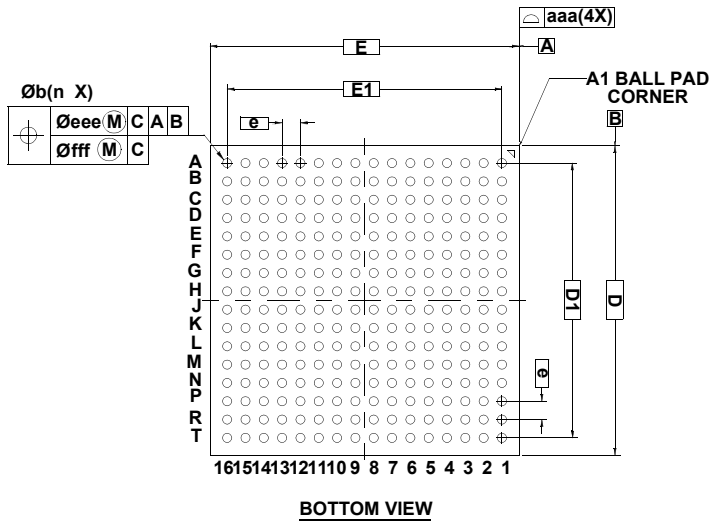
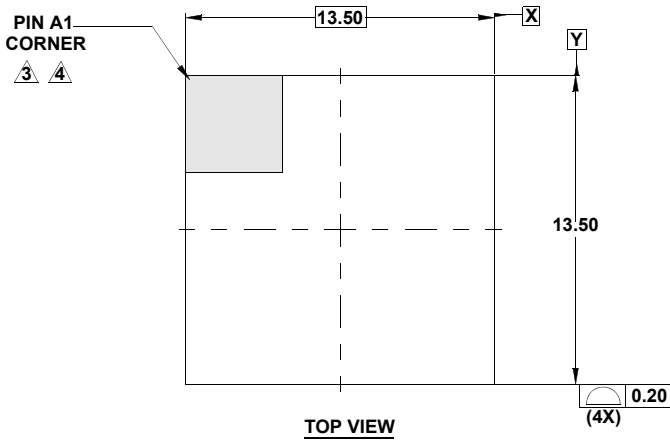
Plastic Packages for Integrated Circuits

Package Outline Drawing

V256.13.5x13.5

256 LOW PROFILE, FINE PITCH PLASTIC BALL GRID ARRAY PACKAGE (LFBGA)

Rev 0, 3/13



NON SOLDER MASK DEFINED
PAD 0.38 NOM/0.40mm
DIAMETER MAX.

		SYMBOL	COMMON DIMENSIONS		
			MIN	NOM	MAX
Package			LFBGA		
Body Size	X	E	13.50		
	Y	D	13.50		
Ball Pitch		e	0.800		
Total Thickness		A	-	-	1.700
Mold Thickness		M	0.700 Ref.		
Substrate Thickness		S	0.560 Ref.		
Ball Diameter			0.400		
Stand Off		A1	0.270	-	0.370
Ball Width		b	0.380	-	0.480
Package Edge Tolerance		aaa	0.150		
Mold Parallelism		bbb	0.200		
Coplanarity		ddd	0.120		
Ball Offset (Package)		eee	0.150		
Ball Offset (Ball)		fff	0.080		
Ball Count		n	256		
Edge Ball Center to Center	X	E1	12.000		
	Y	D1	12.000		

